

PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Chia-Chun YEH</td> <td>02/19/2013</td> </tr> <tr> <td>Xue-Hung TSAI</td> <td>02/19/2013</td> </tr> <tr> <td>Cheng-Hang HSU</td> <td>02/19/2013</td> </tr> <tr> <td>Wei-Tsung CHEN</td> <td>02/19/2013</td> </tr> <tr> <td>Ted-Hong SHINN</td> <td>02/19/2013</td> </tr> </tbody> </table>		Name	Execution Date	Chia-Chun YEH	02/19/2013	Xue-Hung TSAI	02/19/2013	Cheng-Hang HSU	02/19/2013	Wei-Tsung CHEN	02/19/2013	Ted-Hong SHINN	02/19/2013
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<table border="1"> <tr> <td>Name:</td> <td>E Ink Holdings Inc.</td> </tr> <tr> <td>Street Address:</td> <td>NO 3. LI SHIN RD. 1, SCIENCE-BASED INDUSTRIAL PARK</td> </tr> <tr> <td>City:</td> <td>HSINCHU</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> </table>		Name:	E Ink Holdings Inc.	Street Address:	NO 3. LI SHIN RD. 1, SCIENCE-BASED INDUSTRIAL PARK	City:	HSINCHU	State/Country:	TAIWAN				
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CORRESPONDENCE DATA													
<p>Fax Number: 8883886582 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: (888)388-6609 Email: info@ckc-ip.com Correspondent Name: CKC & Partners Co., Ltd. Address Line 1: 12th Floor, Ruttonjee House 11 Duddell Address Line 2: Street Address Line 4: Hong Kong, HONG KONG</p>													
ATTORNEY DOCKET NUMBER:	TWT02506/US												
NAME OF SUBMITTER:	James Lynn O'Sullivan												
<p>Total Attachments: 2 source=TWT02506US-Assignment#page1.tif source=TWT02506US-Assignment#page2.tif</p>													

CH \$40.00 13781780

ASSIGNMENT

This assignment agreement is applicable to an invention entitled (Invention Title) THIN FILM TRANSISTOR STRUCTURE AND ARRAY SUBSTRATE USING THE SAME

The PATENT RIGHTS referred to in this agreement are:

- (check one) ☒ a patent application for this invention, executed by the ASSIGNOR(S) concurrently with this assignment.
- ☐ U.S. patent application Serial No. _____, filed _____
- ☐ a U.S. patent application based on PCT International Application No. _____ filed on (date) _____ (U.S. patent application Serial No. _____, if known).
- ☐ U.S. patent No. _____, issued _____.

The PATENT RIGHTS also include all divisions, reissues, continuations and extensions of the patents and patent applications identified above.

The PATENT RIGHTS assigned under this agreement are:

- (check one) ☒ U.S. patent rights only.
- ☐ Worldwide patent rights. In this case, the assignee shall have the right to claim the benefit of the filing date of any U.S. or foreign patent application for this invention.

The ASSIGNOR(S) referred to in this agreement is (or are) the inventor(s) whose signatures appear on page 2 of this Assignment and any Supplemental Sheet(s).

The ASSIGNEE referred to in this agreement is:

(Name of Assignee) E Ink Holdings Inc.

(Address) NO 3, LI SHIN RD. 1, SCIENCE-BASED INDUSTRIAL PARK, HSINCHU, TAIWAN, R.O.C.

The ASSIGNEE is:

- (check one) ☐ An individual.
- ☐ A Partnership.
- ☒ A Corporation of TAIWAN, R.O.C. (specify state or country)
- ☐ (other) _____

The ASSIGNOR(S), in consideration of \$10.00 paid by the ASSIGNEE, and other good and valuable consideration, receipt of which is acknowledged, hereby assign(s) the following rights to the ASSIGNEE, its successors and assigns:

- the full and exclusive right to the invention;
- the entire right, title and interest in and to the PATENT RIGHTS;
- the right to sue and recover for any past infringement; and
- the right to claim priority under 35 USC 119, 35 USC 120, or any other applicable provisions, based on any earlier patent applications for this invention.

THIS IS PAGE 2 OF AN ASSIGNMENT FROM THE INVENTOR(S) TO

ASSIGNEE: E Ink Holdings Inc.

INVENTION TITLE: THIN FILM TRANSISTOR STRUCTURE AND ARRAY
SUBSTRATE USING THE SAME

As to all U.S. patent applications assigned under this agreement, the ASSIGNOR(S) hereby authorize(s) and request(s) the Commissioner of Patents and Trademark to issue all Letters Patent to the ASSIGNEE as the assignee of the entire right, title and interest, for the sole use and enjoyment of said ASSIGNEE, its successors and assigns.

Further, the ASSIGNOR(S) agree(s) to communicate to said ASSIGNEE, or its representatives, any fact known to the ASSIGNOR(S) with respect to said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitute, renewal, reexamination and reissue applications, execute all necessary assignment papers to cause and all Letter Patent to be issued to said ASSIGNEE, make all rightful oaths and generally do everything necessary or desirable to aid said ASSIGNEE, its successors and assigns, to obtain and enforce proper protection for said invention.

The ASSIGNOR(S) authorize(s) the attorneys and agents who have the power of attorney in this application to check any appropriate boxes and to insert the Serial Number and filing date in this document after it has been executed.

<u>Chia-Chun YEH</u>	<u>Chia-Chun Yeh</u>	<u>2013/02/19</u>
Name of sole or first inventor	Signature	Date

<u>Xue-Hung TSAI</u>	<u>Xue-Hung Tsai</u>	<u>2013/02/19</u>
Name of second inventor, if any	Signature	Date

<u>Cheng-Hang HSU</u>	<u>Cheng-Hang Hsu</u>	<u>2013/02/19</u>
Name of third inventor, if any	Signature	Date

<u>Wei-Tsung CHEN</u>	<u>Wei-Tsung Chen</u>	<u>2013/02/19</u>
Name of fourth inventor, if any	Signature	Date

<u>Ted-Hong SHINN</u>	<u>Ted Hong Shinn</u>	<u>2013/02/19</u>
Name of fifth inventor, if any	Signature	Date